

isola[®]
THE BASE FOR INNOVATION[™]

2025

PRODUCT GUIDE

HIGH PERFORMANCE
LAMINATE & PREPREG
MATERIALS FOR PCB
MANUFACTURING

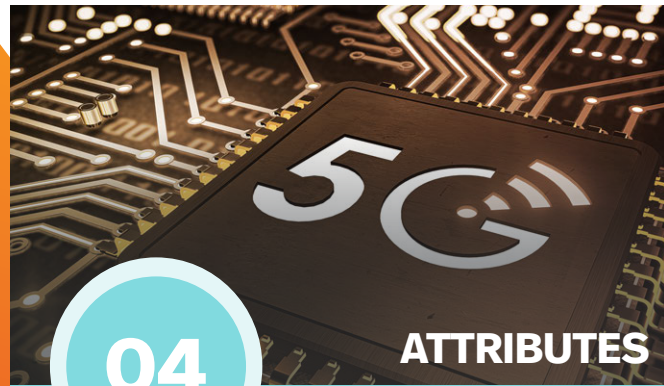


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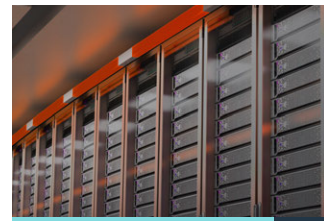
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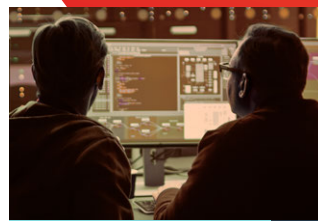
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LAMINATE
& PREPREG
GUIDE



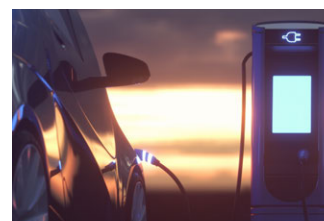
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ABOUT US

GLOBAL HEADQUARTERS, CHANDLER AZ

The highest quality raw materials, supported by truly global, holistic teams of professionals. Isola products are The Base for Innovation®, and it's our goal to foster breakthroughs that make a difference every day.

COMPANY OVERVIEW

Isola is a leader in global material sciences. We design, develop, manufacture, and qualify copper-clad laminates and dielectric prepregs used to fabricate multilayer printed circuit boards (PCBs).

GLOBAL PRESENCE

Isola has manufacturing, research and development, technical support and sales teams across Asia, Europe, and the United States. Why is that important? It allows us to service customers all around the world from start to finish. Knowledge sharing and collaboration is at the heart of our values, and our global teams work closely together to deliver our very best solutions, every single time.

OUR MISSION


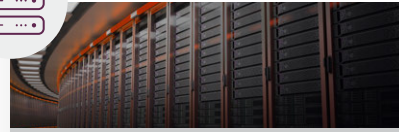
Enable innovation and technology with valued products, services, and technological solutions developed through a deep understanding of customer needs and investments in a highly talented, committed and motivated workforce.

MARKETS

Dive into the markets we've served the most and see how we address the priorities of customers in vastly different worlds with the same consistent, high-performing products, vetted and tested before they ever leave our facilities.

ATTRIBUTES

We possess an extensive portfolio of patent and other intellectual property rights covering our proprietary resin formulations, and have pioneered the development of several product categories with "best in class" technology.

NETWORKING & COMMUNICATION

Isola helps connect the world with highly reliable and thermally robust materials.






5G APPLICATIONS

Isola 5G materials are designed for low moisture uptake and stable electrical performance across a wide range of temperatures to handle anticipated environmental conditions.




RADIO FREQUENCY & MICROWAVE

Isola helps designers achieve smaller, more powerful and durable and less power hungry products.

AUTOMOTIVE & TRANSPORTATION

Isola drives innovation into automobile, railway and aircraft electronics with thermally reliable laminate materials.






AEROSPACE & DEFENSE

Isola offers high reliability and superior performance laminate materials for extreme conditions




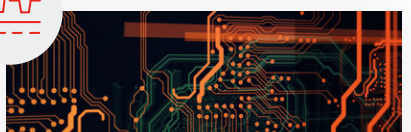

HIGH SPEED DIGITAL (HSD)

Isola offers a wide range of HSD materials that deliver superior performance and CAF resistance.

HIGH THERMAL RELIABILITY

Isola offers several products with different levels of electrical performance that all possess excellent thermal reliability.

HIGH DENSITY INTERCONNECT (HDI)

HDI attributes are PCB designs that employ increased feature density to achieve lighter weight, reduced layer count, and thinner stack ups.




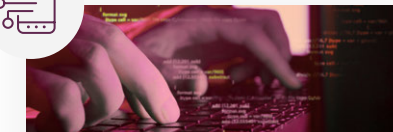

COMPUTING, STORAGE & PERIPHERALS

Isola's high-speed digital materials are the base for the internet of things.






MEDICAL, INDUSTRIAL & INSTRUMENTATION

Isola's materials help cost savings for today's advanced electronics.



CONSUMER ELECTRONICS

Isola's materials help put the consumer in control of their electronic devices.

HALOGEN FREE

Isola offers a variety of non-halogenated materials to meet the industry's increased performance demands for eco-friendly designs.

HIGH TEMPERATURE

Isola offers materials designed for demanding high temperature printed circuit applications.




RADIO FREQUENCY & MICROWAVE

Today's designers are challenged with the task of achieving an optimal balance between cost and performance when selecting base materials.



TERRAGREEN® 400G2

Halogen-Free, Extremely Low Loss Material

TerraGreen® 400G2 laminate materials are our most advanced ultra-high speed, halogen-free extremely-low loss design solution.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 10 mil (0.05 to 0.25 mm)

Copper Foil Type

- HLVP3 (VLP1) ≤ 1.1 micron Rz JIS

Copper Weight

- 1/2, 1 oz (18 and 35 μ m) available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels available
- Moisture barrier packaging

Glass Fabric Availability

- Ultra Low Dk glass
- Mechanically spread glass
- Square weave glass
- Mechanically spread glass

TerraGreen® 400G2 is our halogen-free material solution for next generation 5G infrastructure, data center systems, high end computing, wired & wireless communications and AI applications. Our novel resin system, using ultra smooth HVLP3 (VLP1) copper foil and 2nd generation ultra low Dk glass has been engineered for very high data rates of >100 Gb/s with excellent cost for loss performance.

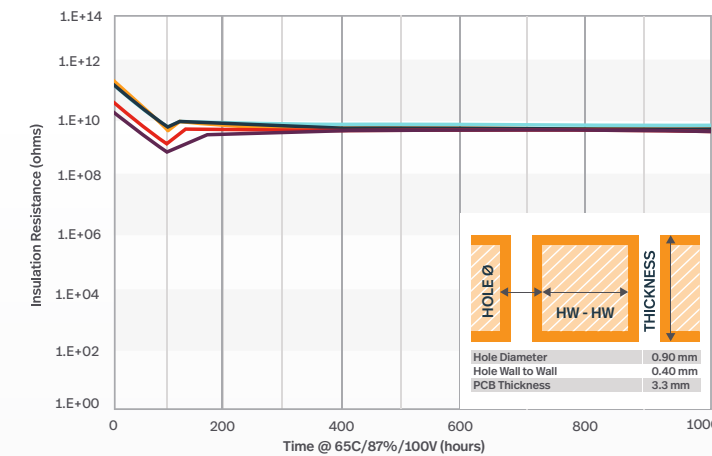
The TerraGreen 400G2 resin system has proven superior CAF performance on tight pitch testing. CAF performance is enhanced by the resin systems excellent interlaminar and bond line adhesion strength.

TerraGreen 400G2 is lead free compatible and sequential lamination capable and can be processed utilizing standard PCB equipment and processing steps. TerraGreen 400G2 meets UL94 V-0.

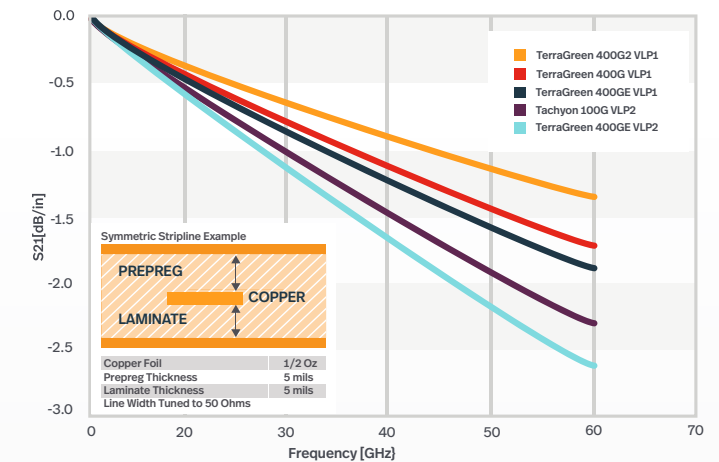
HIGH SPEED DIGITAL

Isola offers a wide range of High-speed Digital (HSD) materials that deliver superior performance and CAF resistance. These low-loss materials are targeted for applications that require high reliability and signal integrity. Isola also offers halogen-free HSD materials for green electronics.

CAF Resistance Data - MRTV



Insertion Loss Over Frequency



Tg	Td	T-260	T-288	Dk		Df		TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI
°C	°C	min	min	2GHz	10GHz	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
200	380	≥ 60	≥ 60	3.10	3.10	0.0015	0.0015	4.10	<0.1	140	2

MARKETS



ATTRIBUTES



TERRAGREEN® 400G

Halogen-Free, Extremely Low Loss Laminate and Prepreg

TerraGreen® 400G laminate materials are our most advanced ultra high speed, extremely low loss design solution.



TerraGreen® 400G is our halogen-free material solution for next generation 5G infrastructure, data center systems, high end computing, wired & wireless communications and AI applications. Our novel resin system using ultra smooth HVLP3 (VLP1) copper foil and Low Dk glass has been engineered for very high data rates of >100 Gb/s with excellent cost for loss performance.

The TerraGreen 400G resin system has proven superior CAF performance on tight pitch testing. CAF performance is enhanced by the resin systems excellent interlaminar and bond line adhesion strength. TerraGreen 400G is lead free compatible and sequential lamination capable and can be processed utilizing standard PCB equipment and processing steps. TerraGreen 400G meets UL94 V-0.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 10 mil (0.05 to 0.25 mm)

Copper Foil Type

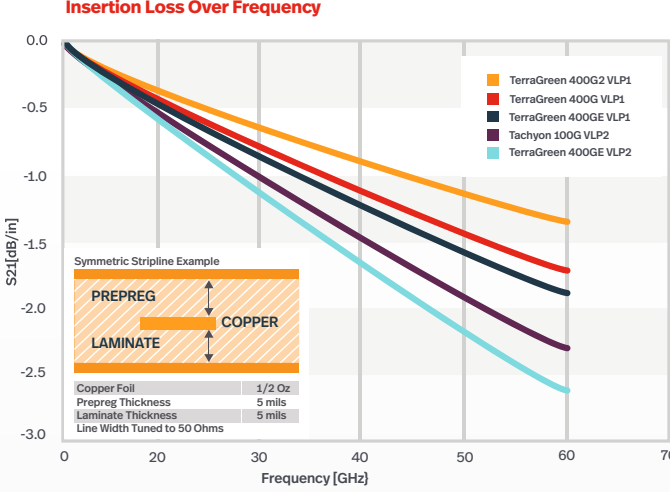
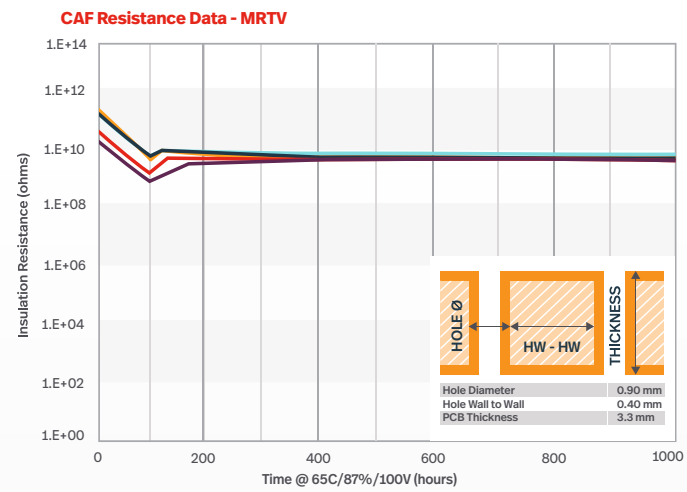
- HLVP3 (VLP1) ≤ 1.1 micron Rz JIS
- Advanced RTF ≤ 2.1 micron Rz JIS
- **Copper Weight**
- 1/2, 1 and 2 oz (18, 35 and 70 μ m) available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels available
- Moisture barrier packaging

Glass Fabric Availability

- Low Dk glass
- Square weave glass
- Mechanically spread glass



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS		
200	380	≥ 60	≥ 60	3.15	3.15	0.0017	0.0017	4.10	<0.1	140	2

MARKETS

ATTRIBUTES

TERRAGREEN® 400GE

Halogen-Free, Ultra Low Loss Material

TerraGreen® 400GE laminate materials are our most advanced ultra-high speed, halogen-free ultra-low loss design solution.



TerraGreen® 400GE is our halogen-free material solution for next generation 5G infrastructure, data center systems, high end computing, wired & wireless communications with data rates >100 Gb/s. Our novel resin system using RTF3 (<2.5 μ m Rz JIS) copper foil and e-glass is our lowest cost member of the TerraGreen® 400G family of products.

The TerraGreen 400GE resin system has proven superior CAF performance on tight pitch testing. CAF performance is enhanced by the resin systems excellent interlaminar and bond line adhesion strength.

TerraGreen 400GE is lead free compatible and sequential lamination capable and can be processed utilizing standard PCB equipment and processing steps. TerraGreen 400GE meets UL94 V-0.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 10 mil (0.05 to 0.25 mm)

Copper Foil Type

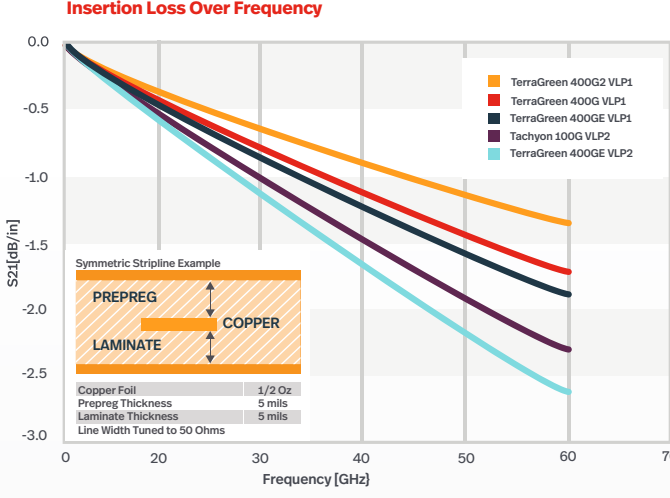
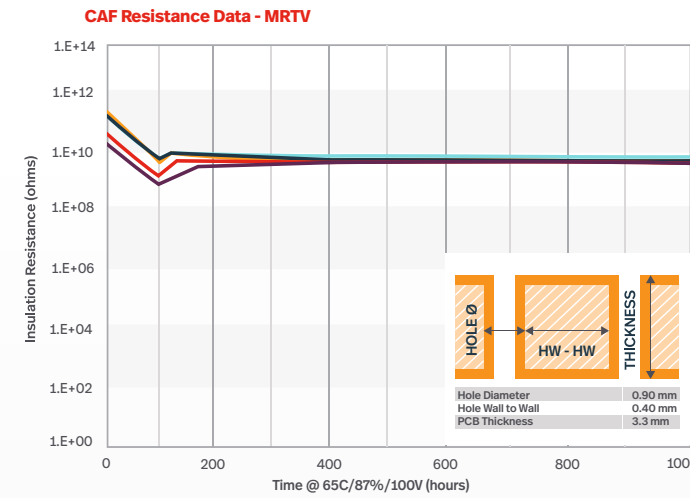
- HVLP3 (VLP1) ≤ 1.1 micron Rz JIS
- Advanced RTF ≤ 2.1 micron Rz JIS
- **Copper Weight**
- 1/2, 1 and 2 oz (18, 35 and 70 μ m) available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels available
- Moisture barrier packaging

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS		
200	380	≥ 60	≥ 60	3.29	3.29	0.0026	0.0026	4.10	<0.1	140	2

MARKETS

ATTRIBUTES

TACHYON® 100G

Ultra Low Loss Laminate and Prepreg

Tachyon® 100G laminate materials are designed for very high-speed digital applications up to and beyond data rates of 100 Gb/s.



PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 20 mil (0.05 to 0.50 mm)

Copper Foil Type

- HLVP3 (VLP1) ≤ 1.1 micron Rz JIS
- HVLP (VLP2) ≤ 2.5 micron Rz JIS
- Advanced RTF ≤ 2.1 micron Rz JIS
- Embedded resistor foil

Copper Weight

- 1/2, 1 and 2 oz (18, 35 and 70 μm) available
- Heavier copper foil available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Moisture barrier packaging
- Tooling of prepreg panels available

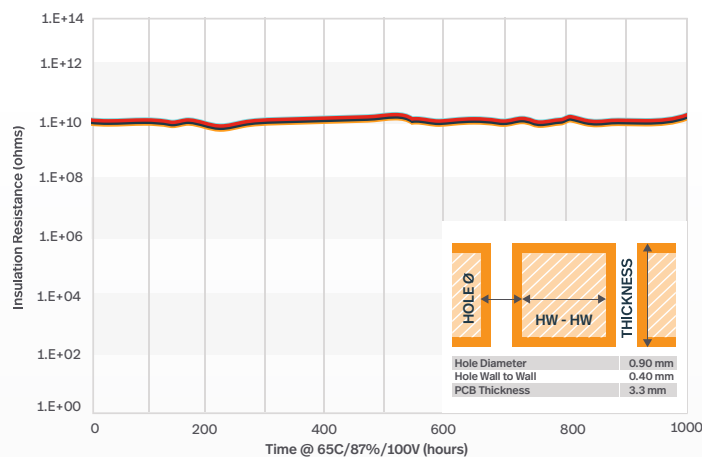
Glass Fabric Availability

- Low Dk Glass
- Square weave glass
- Mechanically spread glass

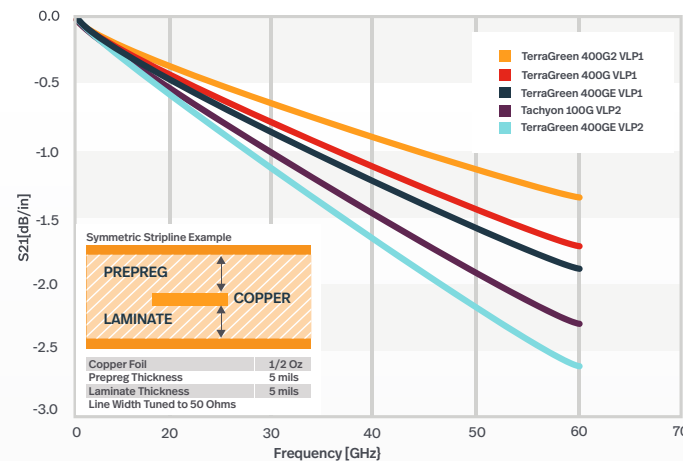
Tachyon® 100G materials exhibit exceptional electrical properties that are very stable over a broad frequency and temperature range between -55°C and +125°C up to 100 GHz. These electrical properties provide designers a scalable solution for next generation designs of backplanes and daughter cards, enabling 10x improvements from 10 Gb/s data rates.

Isola has developed Tachyon 100G with the highest level of thermal performance for high layer count line cards. The very low Z-axis CTE makes it a perfect choice for fine pitch BGA applications. The material is optimized with the use of spread glass to mitigate skew, improve rise times, reduce jitter, and increase eye width/height and that use ultra smooth HVLP (VLP2) 2um Rz copper that significantly reduces conductor losses.

CAF Resistance Data - MRTV



Insertion Loss Over Frequency



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
215	360	≥ 60	≥ 60	3.04	3.02	5.50	<0.1	130	3

MARKETS



ATTRIBUTES



I-TERA® MT40

Very Low Loss Laminate and Prepreg



PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 24 mil (0.05 to 0.61 mm)

Copper Foil Type

- HVLP (VLP2) ≤ 2.5 micron Rz JIS
- Advanced RTF ≤ 2.1 micron Rz JIS
- RTF (Reverse Treat Foil)
- Embedded resistor foil

Copper Weight

- 1/2 to 2 oz (18, 35 and 70 μm) is standard
- Heavier copper foil available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

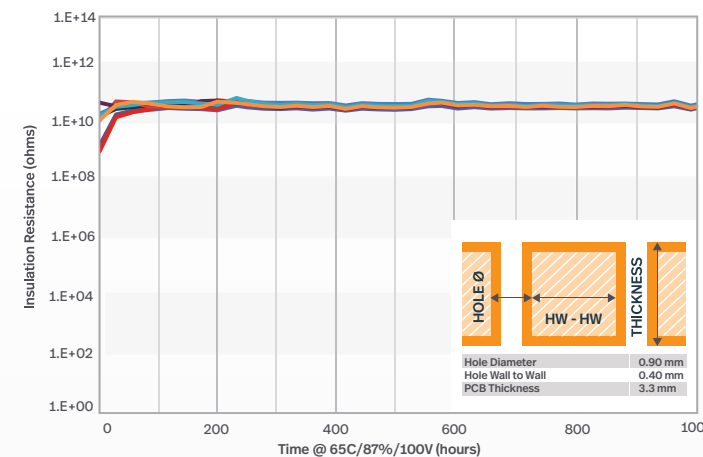
Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass

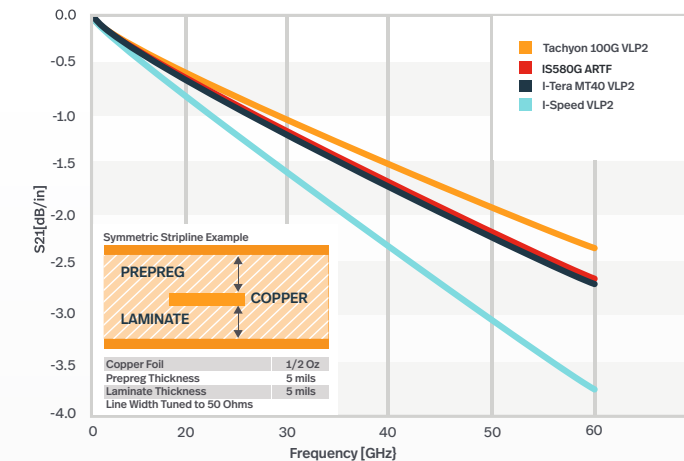
I-Tera® MT40 is suitable for many of today's high speed digital and RF/microwave printed circuit designs. I-Tera MT40 features a dielectric constant (Dk) that is stable between -55°C and +125°C up to W-band frequencies. In addition, I-Tera MT40 offers a lower dissipation factor (Df) of 0.0031 making it a cost effective alternative to PTFE and other commercial microwave and high-speed digital laminate materials.

I-Tera MT40 laminate materials are currently being offered in both laminate and prepreg form in typical thicknesses and standard panel sizes. This provides a complete materials solution package for high-speed digital multilayer, hybrid, RF/microwave, multilayer and double-sided printed circuit designs. I-Tera MT40 does not require any special through hole treatments commonly needed when processing PTFE-based laminate materials.

CAF Resistance Data - MRTV



Insertion Loss Over Frequency



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
215	360	≥ 60	≥ 60	3.45	3.45	5.70	<0.1	130	3

MARKETS



ATTRIBUTES



IS580G

Halogen-Free, Very Low Loss Material

IS580G is a halogen-free 195°C Tg resin system for multilayer PWB applications where maximum thermal performance and reliability are required.



IS580G laminate and prepreg products are manufactured with Isola's high performance, low loss, multi-functional resin system, reinforced with electrical grade (e-glass) glass fabric. The unique resin system delivers a >25% improvement in Z-axis expansion while maintaining good flow and fill properties. These properties, coupled with superior moisture resistance at reflow, result in a halogen-free product with an industry-leading combination of thermal and electrical performance.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 30 mil (0.05 to 0.75 mm)

Copper Foil Type

- Advanced RTF ≤ 2.5 micron Rz JIS

Copper Weight

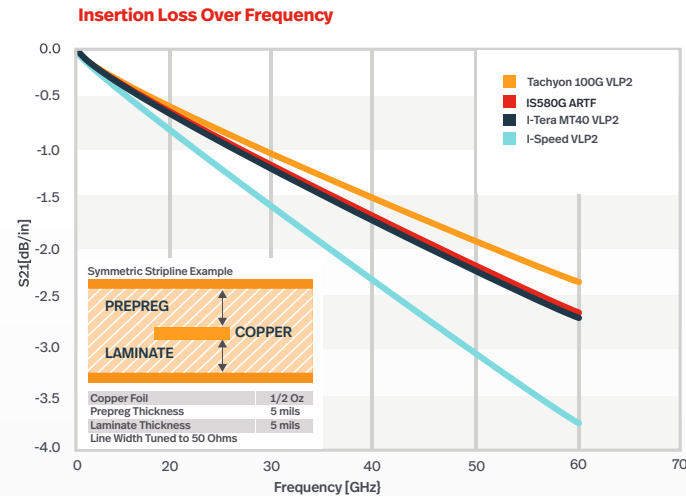
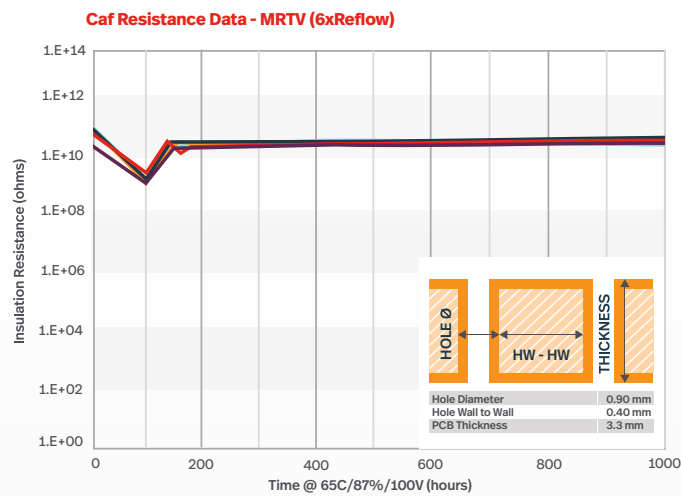
- 1/2, 1 and 2 oz (18, 35 and 70 μm) available

Standard Material Offering: Prepreg

- Roll or panel form
- Moisture barrier packaging
- Tooling of prepreg panels

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH (HTE)	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS		
195	385	≥ 60	≥ 60	3.80	3.80	0.006	0.006	4.30	<0.1	160	2

MARKETS



ATTRIBUTES



I-SPEED®

Low Loss, Epoxy Laminate and Prepreg

I-Speed® is a 180°C Tg FR-4 resin system for multilayer PWB applications where maximum thermal performance and reliability are required.



I-Speed® laminate and prepreg products are manufactured with Isola's patentable high performance multi-functional resin system, reinforced with electrical grade (e-glass) glass fabric. This system delivers a low Z-axis expansion and offers 25% reduction in loss compared to our mid-loss products. These properties coupled with superior moisture resistance at reflow, result in a product that bridges the gap from both a thermal and electrical perspective.

The I-Speed resin system is laser fluorescing and UV blocking for maximum compatibility with Automated Optical Inspection (AOI) systems, optical positioning systems and photo imangible solder mask imaging.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 28 mil (0.05 to 0.71 mm)

Copper Foil Type

- HTE Grade 3
- HVLP (VLP2) ≤ 2.5 micron Rz JIS
- RTF (Reverse Treat Foil)
- Embedded resistor foil

Copper Weight

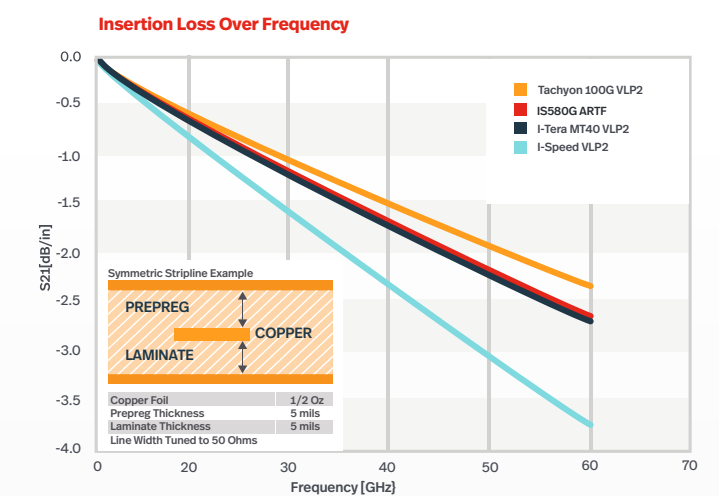
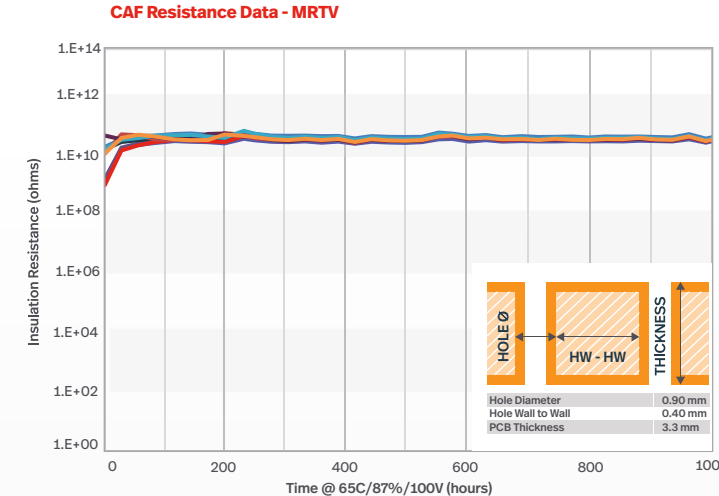
- 1/2 to 2 oz (18, 35 and 70 μm) is standard
- Heavier copper foil available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS		
180	360	>60	≥ 60	3.64	3.63	0.0059	0.0060	5.50	<0.06	130	2

MARKETS



ATTRIBUTES



ASTRA® MT77

Ultra Low Loss Laminate and Prepreg

Astra® MT77 materials are a breakthrough, very low-loss dielectric constant (Dk) product for millimeter wave frequencies and beyond.



PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2.5, 5, 7.5, 10, 12.5, 15, 20, 30, 60 mil (0.0635, 0.127, 0.1905, 0.254, 0.3175, 0.381, 0.510, 0.760, 1.50 mm)

Copper Foil Type

- HVLP (VLP2) ≤2.5 micron Rz JIS
- Embedded resistor foil

Copper Weight

- ½ to 2 oz (18,35 and 70 µm) is standard
- Thinner copper foil available

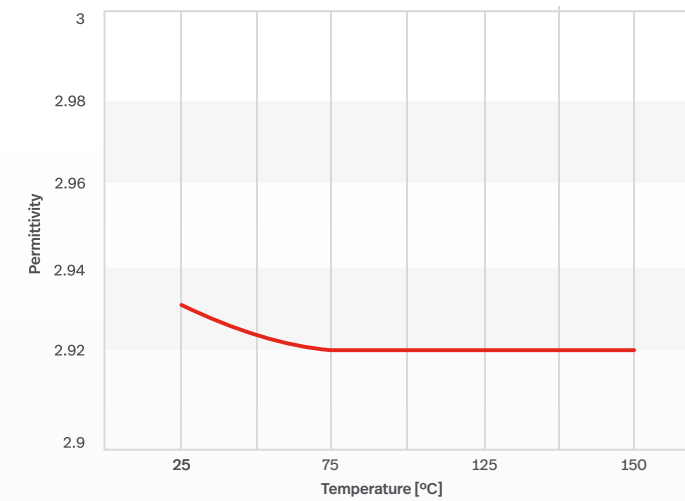
Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

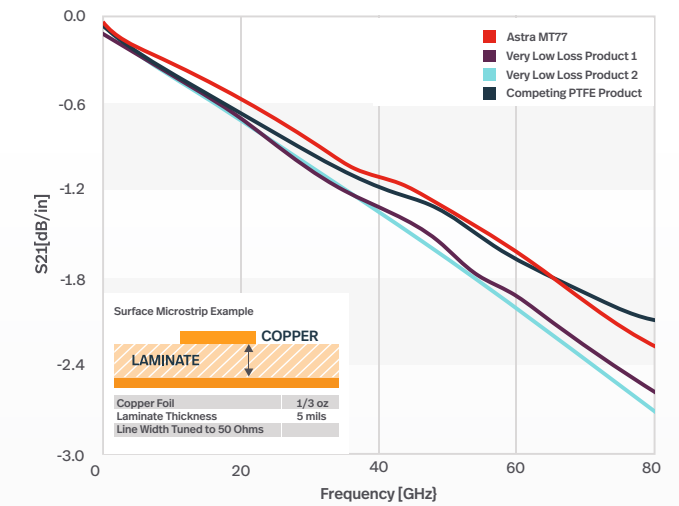
Astra® MT77 laminate materials exhibit exceptional electrical properties which are very stable over a broad frequency and temperature range. Astra MT77 is suitable for many of today's commercial RF/microwave printed circuit designs. It features a dielectric constant (Dk) that is stable between -40°C and +140°C at up to W-band frequencies. In addition, Astra MT77 offers an ultra-low dissipation factor (Df) of 0.0017, making it a cost-effective alternative to PTFE and other commercial microwave laminate materials.

Key applications include long antennas and radar applications for automobiles, such as adaptive cruise control, pre-crash, blind spot detection, lane departure warning and stop and go systems.

Permittivity @60GHz



Insertion Loss Over Frequency



RADIO FREQUENCY & MICROWAVE

Today's RF/Microwave and Millimeter Wave designers are challenged more than ever with the task of achieving an optimal balance between cost and performance when selecting base materials.

Tg	Td	T-260	T-288	Dk		Df		TYPICAL PEEL STRENGTH	MOISTURE ABSORPTION	UL	CTI
°C	°C	min	min	2GHz	10GHz	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
200	360	≥60	≥60	3.00	3.00	0.0017	0.0017	5.70	<0.1	130	3

MARKETS



ATTRIBUTES



I-TERA® MT40 (RF/MW)

Very Low Loss Laminate

I-Tera® MT40 laminate materials exhibit exceptional electrical properties which are very stable over a broad frequency and temperature range.



I-Tera® MT40 is suitable for many of today's high speed digital and RF/microwave printed circuit designs. I-Tera MT40 features a dielectric constant (Dk) that is stable between -40°C and +140°C up to W-band frequencies. In addition, I-Tera MT40 offers a very low dissipation factor (Df) of 0.0028 - 0.0035 making it a cost effective alternative to PTFE and other commercial microwave and high-speed digital laminate materials.

I-Tera MT40 laminate materials are currently being offered in both laminate and prepreg form in typical thicknesses and standard panel sizes. This provides a complete materials solution package for high-speed digital multilayer, hybrid, RF/microwave, multilayer and double-sided printed circuit designs. I-Tera MT40 does not require any special through hole treatments commonly needed when processing PTFE-based laminate materials.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 5, 10, 20, 30, 40, 60 mil (0.13, 0.25, 0.51, 0.76, 1.02, 1.5 mm)

Copper Foil Type

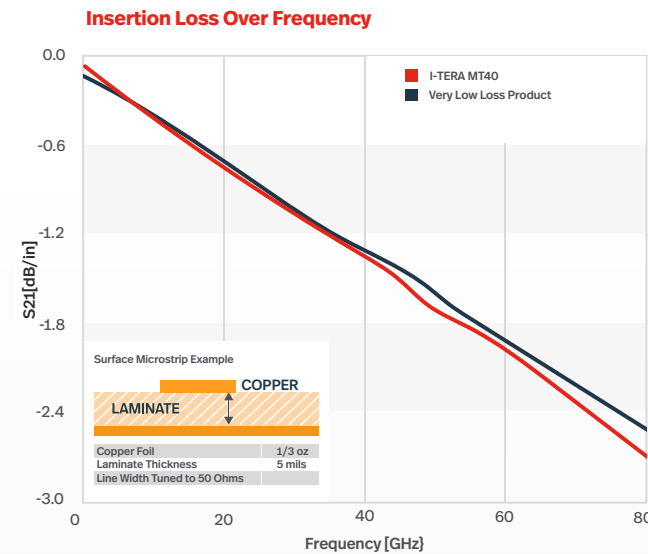
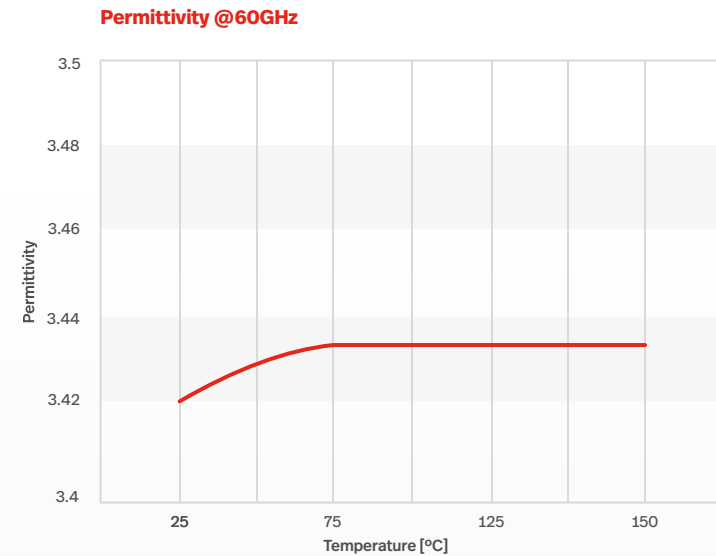
- HTE Grade 3
- HVLP (VLP2) ≤ 2.5 micron Rz JIS
- Advanced RTF ≤ 2.1 micron Rz JIS
- RTF (Reverse Treat Foil)
- Embedded resistor foil

Copper Weight

- $\frac{1}{2}$ to 2 oz (18,35 and 70 μ m) is standard
- Thinner copper foil available

Glass Fabric Availability

- Square weave glass
- Mechanically spread glass



Tg	Td	T-260	T-288	Dk		Df		TYPICAL PEEL STRENGTH (HTE)	MOISTURE ABSORPTION	UL	CTI
°C	°C	min	min	2GHz	10GHz	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
215	360	≥ 60	≥ 60	3.38, 3.45, 3.60, 3.75	3.38, 3.45, 3.60, 3.75	0.0028 to 0.0035	0.0028 to 0.0035	5.7	<0.1	130	3

MARKETS



ATTRIBUTES



HIGH THERMAL RELIABILITY

Thermal reliability requirements can be separated into two categories. The first involves survival of a PCB through assembly without defects such as blisters or delamination. The second category involves thermal reliability in the operating environment over a product's lifetime. Both types of thermal reliability are critical.

IS550H

High Reliability Laminate and Prepreg

IS550H is our halogen-free laminate solution for high power & voltage applications that require extreme thermal stability.



IS550H was developed in conjunction with a consortium of industry experts for high power & high voltage applications and PEV & HEV automotive electrification. The resulting solution addresses critical application needs for use in a harsh environment where very demanding, long term thermal reliability performance, extreme thermal cycling and very high voltage CAF & electro-migration resistance are required.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 59 mil (0.05 to 1.5 mm)

Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)

Copper Weight

- ½, 1 and 2 oz (18, 35 and 70 µm) is standard
- Heavier copper available

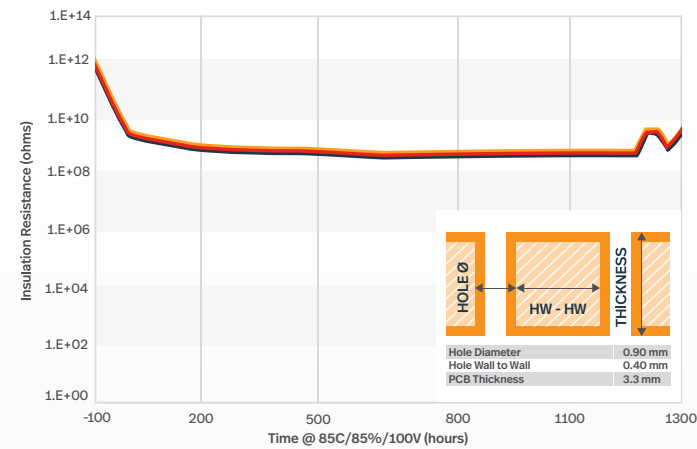
Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass

CAF Resistance Data - MRTV



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH (HTE)	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
200	400	≥60	≥60	4.50	4.43	0.014	0.016	8.2	<0.25	150	3

MARKETS



ATTRIBUTES



370HR

Industry Leading Epoxy Laminate and Prepreg

370HR is the industry's "best in class" lead-free compatible product for high-reliability applications across a wide range of markets.



370HR laminates and prepregs, designed by Polyclad, are made using a patented high performance 180°C Tg FR-4 multifunctional epoxy resin system that is designed for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required. We manufacture 370HR laminates and prepregs with high quality E-glass glass fabric for superior Conductive Anodic Filament (CAF) resistance. 370HR provides superior thermal performance with low Coefficient of Thermal Expansion (CTE) and the mechanical, chemical and moisture resistance properties that equal or exceed the performance of traditional FR-4 materials.

370HR is used in thousands of PWB designs and has proven to be best in class for thermal reliability, CAF performance, ease of processing and proven performance on sequential lamination designs.

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 125 mil (0.05 to 3.2 mm)

Copper Foil Type

- HTE Grade 3
- RTF (Reverse Treat Foil)
- Embedded resistor foil

Copper Weight

- ½ to 2 oz (18,35 and 70 µm) is standard
- Heavier copper available
- Thinner copper foil available

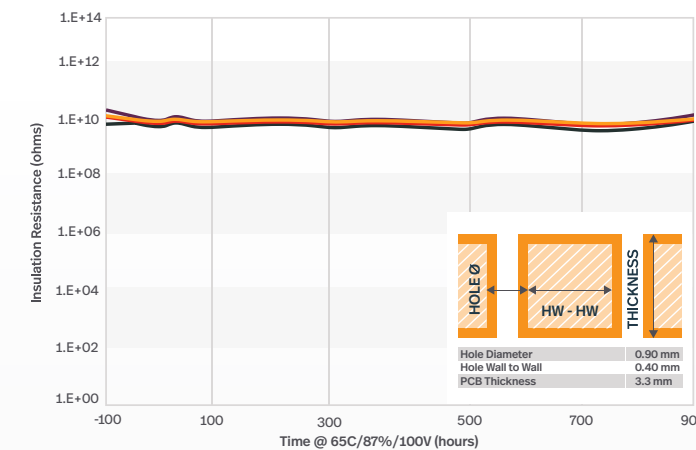
Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

Glass Fabric Availability

- E-glass
- Square weave glass
- Mechanically spread glass

CAF Resistance Data - MRTV



Tg	Td	T-260	T-288	Dk	Df	TYPICAL PEEL STRENGTH (HTE)	MOISTURE ABSORPTION	UL	CTI		
°C	°C	min	min	2GHz	10GHz	2GHz	10GHz	LB/IN	%	RTI °C	UL CLASS
180	340	≥60	≥30	4.04	3.92	0.021	0.025	7.00	<0.15	130	3

MARKETS



ATTRIBUTES



PCB LAMINATE & PREPREG

MATERIALS

Isola high-performance laminate products feature proprietary resin formulations that are engineered to meet your design specifications and exceed your expectations.

RF / MICROWAVE

HIGH SPEED DIGITAL

THERMAL RELIABILITY

I-TERA® MT40 (RF/MW)

Very Low Loss Material

Tg: 215°C Dk: 3.38/3.45/3.60/3.75
Td: 360°C Df: 0.0028 - 0.0035



ASTRA® MT77

Ultra Low Loss, RF/MW Laminate and Prepreg

Tg: 200°C Dk: 3.00
Td: 360°C Df: 0.0017



TERRAGREEN® 400G RF/MW

Extremely Low Loss Material

Tg: 210°C Dk: 3.07
Td: 400°C Df: 0.0018



I-TERA® MT40

Very Low Loss Laminate and Prepreg

Tg: 215°C Dk: 3.45
Td: 360°C Df: 0.0031



TACHYON® 100G

Very Low Loss Laminate and Prepreg

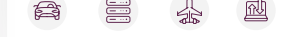
Tg: 215°C Dk: 3.02
Td: 360°C Df: 0.0021



TERRAGREEN® 400G2

Extremely Low Loss Laminate and Prepreg

Tg: 200°C Dk: 3.10
Td: 380°C Df: 0.0015



TERRAGREEN® 400G

Extremely Low Loss Laminate and Prepreg

Tg: 200°C Dk: 3.10
Td: 380°C Df: 0.0018



TERRAGREEN® 400GE

Extremely Low Loss Laminate and Prepreg

Tg: 200°C Dk: 3.29
Td: 380°C Df: 0.0026



ISS80G

Very Low Loss Material

Tg: 195°C Dk: 3.80
Td: 385°C Df: 0.0060



I-SPEED®

Low Loss, Epoxy Laminate and Prepreg

Tg: 180°C Dk: 3.64
Td: 360°C Df: 0.0060



FR408HR

Lead Free, Mid Loss Laminate and Prepreg

Tg: 190°C Dk: 3.68
Td: 360°C Df: 0.0092



NO FLOW

FR406N

No-Flo® and Lo-Flo® Specialty Prepreg

Tg: 170°C Dk: 4.3
Td: 300°C Df: 0.025



P25N

Polyimide UL HB No Flow Prepreg

Tg: 250°C Dk: 3.67
Td: 383°C Df: 0.018



HIGH TEMPERATURE

P95/P25

Polyimide UL HB Laminate and Prepreg

Tg: 260°C Dk: 3.76
Td: 416°C Df: 0.017



P96/26

Polyimide UL V-0 Laminate and Prepreg

Tg: 260°C Dk: 3.76
Td: 396°C Df: 0.017



185HR

Standard Loss, Thermally Robust Epoxy Laminate and Prepreg

Tg: 180°C Dk: 4.01
Td: 340°C Df: 0.020



IS400

Lead Free, Mid Tg Epoxy Laminate and Prepreg

Tg: 150°C Dk: 3.90
Td: 330°C Df: 0.022



IS550H

Low CTE, Very High Thermal Reliability Laminate and Prepreg

Tg: 200°C Dk: 4.43
Td: 400°C Df: 0.016



370HR

Standard Loss, Thermally Robust Epoxy Laminate and Prepreg

Tg: 180°C Dk: 4.04
Td: 340°C Df: 0.021



ATTRIBUTES

	HALOGEN FREE	Tg	Td	T-260	T-288	Z-Axis CTE			Dk		Df		TYPICAL PEEL STRENGTHS	MOISTURE ABSORPTION	UL	CTI	
		°C	°C	min	min	Pre-Tg PPM/°C	Post-Tg PPM/°C	50 to 260 °C %	2GHz	10GHz	2GHz	10GHz					RTI °C
RF/MICROWAVE	TERRAGREEN® 400G RF/MW	•	210	400	≥60	≥60	37	170	3.1	3.07	3.07	0.0018	0.0018	3.5	0.10%	130	2
	I-TERA® MT40 (RF/MW)		215	360	≥60	≥60	55	290	2.8	3.38 to 3.75	3.38 to 3.75	0.0028 to 0.0035	0.0028 to 0.0035	5.7	0.10%	130	3
	ASTRA® MT77		200	360	≥60	≥60	50-70	250-350	2.25-3.15	3.00	3.00	0.0017	0.0017	5.7	0.10%	130	3
HIGH SPEED DIGITAL	FR408HR		190	360	≥60	>30	55	230	2.8	3.68	3.65	0.0092	0.0095	5.5	0.06%	130	2
	I-SPEED®		180	360	≥60	≥60	60	230	2.7	3.64	3.63	0.0059	0.006	5.5	0.06%	130	2
	IS580G	•	195	385	≥60	≥60	30	190	1.8	3.80	3.80	0.006	0.006	4.3	0.05%	160	2
	I-TERA® MT40		215	360	≥60	≥60	55	290	2.8	3.45	3.45	0.0031	0.0031	5.7	0.10%	130	3
	TACHYON® 100G		215	360	≥60	≥60	45	250	2.5	3.04	3.02	0.0021	0.0021	5.5	0.10%	130	3
	TERRAGREEN® 400G	•	200	380	≥60	≥60	37	170	1.8	3.15	3.15	0.0017	0.0017	4.1	0.10%	140	2
	TERRAGREEN® 400GE	•	200	380	≥60	≥60	37	170	1.8	3.29	3.29	0.0026	0.0026	4.1	0.10%	140	2
TERRAGREEN® 400G2	•	200	380	≥60	≥60	37	170	1.8	3.10	3.10	0.0015	0.0015	4.1	0.10%	140	2	
THERMAL RELIABILITY	IS400		150	330	≥60	>10	50	250	3.3	3.90	3.80	0.021	0.026	9.0	0.18%	130	3
	185HR		180	340	≥60	>15	40	220	2.7	4.01	3.88	0.020	0.024	4.5	0.15%	130	3
	370HR		180	340	≥60	≥30	45	230	2.8	4.04	3.92	0.021	0.025	7.0	0.15%	130	3
	IS550H	•	200	400	≥60	≥60	38	210	2.0	4.50	4.43	0.014	0.016	8.2	0.25%	150	3
SPECIALTY PRODUCTS	P95/P25		260	416	≥60	≥60	55	N/A	1.5	3.76	3.73	0.018	0.021	7.0	0.50%	170	2
	P96/P26		260	396	≥60	≥60	55	N/A	1.5	3.76	3.73	0.018	0.021	7.0	0.50%	170	4

ACCORDING TO IPC-4101

		/40	/41	/97	/98	/99	/101	/102	/126	/129	/134	/140
THERMAL RELIABLE	IS400			•	•	•	•					
	185HR				•	•	•		•			
	370HR				•	•	•		•			
	IS550H											•
HIGH SPEED DIGITAL	FR408HR				•	•	•		•			
	I-SPEED®				•	•	•		•			
	IS580G											•
	I-TERA® MT40							•				
	TACHYON® 100G							•				
	TERRAGREEN® 400GE										•	
SPECIALTY PRODUCTS	P95/P25	•	•									
	P96/P26	•	•									

ACCORDING TO IPC-4103

		/17
HIGH SPEED DIGITAL	IS580G®	•
	I-TERA® MT40	•
RF/MICROWAVE	I-TERA® MT40 (RF/MW)	•
	ASTRA® MT77	•

EXPLORE MORE





HYBRID

STACKUPS

Buidling hybrid stackups is easy with Isola laminate & prepreg materials.



GLOBAL

NETWORK

Whether you're just figuring out what you need or you're ready to start building, we're here to collaborate and get your product to market fast.



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- > High Speed Digital + RF/ Microwave parts of I-Tera® MT40
- > Tachyon® 100G + I-Tera® MT40
- > Mix Astra® MT77, I-Tera® MT40, Tachyon® 100G, materials with 370HR

OUR REACH

- 3 GLOBAL HEADQUARTERS
- 3 RESEARCH LABORATORIES
- 6 MANUFACTURING FACILITIES



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Revisions:

A: Initial release - 1/23
B: NEW Products - TerraGreen[®]
400G2, TerraGreen[®] 400GE,
580G - 1/24
C: Corrected Typos - 1/25